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### Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	128300
Number of Logic Elements/Cells	340000
Total RAM Bits	19456000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5sgxma3k3f40c2ln">https://www.e-xfl.com/product-detail/intel/5sgxma3k3f40c2ln</a>

**Table 7. Recommended Transceiver Power Supply Operating Conditions for Stratix V GX, GS, and GT Devices (Part 2 of 2)**

Symbol	Description	Devices	Minimum <sup>(4)</sup>	Typical	Maximum <sup>(4)</sup>	Unit
$V_{CCR\_GXBR}$ <sup>(2)</sup>	Receiver analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCR\_GTBR}$	Receiver analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCT\_GXBL}$ <sup>(2)</sup>	Transmitter analog power supply (left side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GXBR}$ <sup>(2)</sup>	Transmitter analog power supply (right side)	GX, GS, GT	0.82	0.85	0.88	V
			0.87	0.90	0.93	
			0.97	1.0	1.03	
			1.03	1.05	1.07	
$V_{CCT\_GTBR}$	Transmitter analog power supply for GT channels (right side)	GT	1.02	1.05	1.08	V
$V_{CCL\_GTBR}$	Transmitter clock network power supply	GT	1.02	1.05	1.08	V
$V_{CCH\_GXBL}$	Transmitter output buffer power supply (left side)	GX, GS, GT	1.425	1.5	1.575	V
$V_{CCH\_GXBR}$	Transmitter output buffer power supply (right side)	GX, GS, GT	1.425	1.5	1.575	V

**Notes to Table 7:**

- (1) This supply must be connected to 3.0 V if the CMU PLL, receiver CDR, or both, are configured at a base data rate > 6.5 Gbps. Up to 6.5 Gbps, you can connect this supply to either 3.0 V or 2.5 V.
- (2) Refer to Table 8 to select the correct power supply level for your design.
- (3) When using ATX PLLs, the supply must be 3.0 V.
- (4) This value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Table 8 shows the transceiver power supply voltage requirements for various conditions.

**Table 8. Transceiver Power Supply Voltage Requirements**

Conditions	Core Speed Grade	VCCR_GXB & VCCT_GXB <sup>(2)</sup>	VCCA_GXB	VCCH_GXB	Unit
If BOTH of the following conditions are true: <ul style="list-style-type: none"> <li>■ Data rate &gt; 10.3 Gbps.</li> <li>■ DFE is used.</li> </ul>	All	1.05	3.0	1.5	V
If ANY of the following conditions are true <sup>(1)</sup> : <ul style="list-style-type: none"> <li>■ ATX PLL is used.</li> <li>■ Data rate &gt; 6.5Gbps.</li> <li>■ DFE (data rate ≤ 10.3 Gbps), AEQ, or EyeQ feature is used.</li> </ul>	All	1.0			
If ALL of the following conditions are true: <ul style="list-style-type: none"> <li>■ ATX PLL is not used.</li> <li>■ Data rate ≤ 6.5Gbps.</li> <li>■ DFE, AEQ, and EyeQ are not used.</li> </ul>	C1, C2, I2, and I3YY	0.90	2.5		
	C2L, C3, C4, I2L, I3, I3L, and I4	0.85	2.5		

**Notes to Table 8:**

- (1) Choose this power supply voltage requirement option if you plan to upgrade your design later with any of the listed conditions.
- (2) If the VCCR\_GXB and VCCT\_GXB supplies are set to 1.0 V or 1.05 V, they cannot be shared with the VCC core supply. If the VCCR\_GXB and VCCT\_GXB are set to either 0.90 V or 0.85 V, they can be shared with the VCC core supply.

## DC Characteristics

This section lists the supply current, I/O pin leakage current, input pin capacitance, on-chip termination tolerance, and hot socketing specifications.

### Supply Current

Supply current is the current drawn from the respective power rails used for power budgeting. Use the Excel-based Early Power Estimator (EPE) to get supply current estimates for your design because these currents vary greatly with the resources you use.



For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

**Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 2 of 2)**

Symbol	Description	Conditions	Resistance Tolerance				Unit
			C1	C2, I2	C3, I3, I3YY	C4, I4	
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R <sub>S</sub>	Internal series termination without calibration (50-Ω setting)	V <sub>CCIO</sub> = 1.2 V	±35	±35	±50	±50	%
100-Ω R <sub>D</sub>	Internal differential termination (100-Ω setting)	V <sub>CCPD</sub> = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

**Equation 1. OCT Variation Without Recalibration for Stratix V Devices <sup>(1), (2), (3), (4), (5), (6)</sup>**

$$R_{OCT} = R_{SCAL} \left( 1 + \left\langle \frac{dR}{dT} \times \Delta T \right\rangle \pm \left\langle \frac{dR}{dV} \times \Delta V \right\rangle \right)$$

**Notes to Equation 1:**

- (1) The R<sub>OCT</sub> value shows the range of OCT resistance with the variation of temperature and V<sub>CCIO</sub>.
- (2) R<sub>SCAL</sub> is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V<sub>CCIO</sub> at power-up.
- (5) dR/dT is the percentage change of R<sub>SCAL</sub> with temperature.
- (6) dR/dV is the percentage change of R<sub>SCAL</sub> with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

**Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.0297	% / mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	

**Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) <sup>(1)</sup>**

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/ <sup>o</sup> C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

**Note to Table 13:**

(1) Valid for a V<sub>CCIO</sub> range of  $\pm 5\%$  and a temperature range of 0° to 85°C.

**Pin Capacitance**

Table 14 lists the Stratix V device family pin capacitance.

**Table 14. Pin Capacitance for Stratix V Devices**

Symbol	Description	Value	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

**Hot Socketing**

Table 15 lists the hot socketing specifications for Stratix V devices.

**Table 15. Hot Socketing Specifications for Stratix V Devices**

Symbol	Description	Maximum
I <sub>IOPIN</sub> (DC)	DC current per I/O pin	300 $\mu$ A
I <sub>IOPIN</sub> (AC)	AC current per I/O pin	8 mA <sup>(1)</sup>
I <sub>XCVR-TX</sub> (DC)	DC current per transceiver transmitter pin	100 mA
I <sub>XCVR-RX</sub> (DC)	DC current per transceiver receiver pin	50 mA

**Note to Table 15:**

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C \, dv/dt$ , in which C is the I/O pin capacitance and dv/dt is the slew rate.

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 2 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Spread-spectrum downspread	PCIe	—	0 to -0.5	—	—	0 to -0.5	—	—	0 to -0.5	—	%
On-chip termination resistors <sup>(21)</sup>	—	—	100	—	—	100	—	—	100	—	$\Omega$
Absolute $V_{MAX}$ <sup>(5)</sup>	Dedicated reference clock pin	—	—	1.6	—	—	1.6	—	—	1.6	V
	RX reference clock pin	—	—	1.2	—	—	1.2	—	—	1.2	
Absolute $V_{MIN}$	—	-0.4	—	—	-0.4	—	—	-0.4	—	—	V
Peak-to-peak differential input voltage	—	200	—	1600	200	—	1600	200	—	1600	mV
$V_{ICM}$ (AC coupled) <sup>(3)</sup>	Dedicated reference clock pin	1050/1000/900/850 <sup>(2)</sup>			1050/1000/900/850 <sup>(2)</sup>			1050/1000/900/850 <sup>(2)</sup>			mV
	RX reference clock pin	1.0/0.9/0.85 <sup>(4)</sup>			1.0/0.9/0.85 <sup>(4)</sup>			1.0/0.9/0.85 <sup>(4)</sup>			V
$V_{ICM}$ (DC coupled)	HCSL I/O standard for PCIe reference clock	250	—	550	250	—	550	250	—	550	mV
Transmitter REFCLK Phase Noise (622 MHz) <sup>(20)</sup>	100 Hz	—	—	-70	—	—	-70	—	—	-70	dBc/Hz
	1 kHz	—	—	-90	—	—	-90	—	—	-90	dBc/Hz
	10 kHz	—	—	-100	—	—	-100	—	—	-100	dBc/Hz
	100 kHz	—	—	-110	—	—	-110	—	—	-110	dBc/Hz
	$\geq 1$ MHz	—	—	-120	—	—	-120	—	—	-120	dBc/Hz
Transmitter REFCLK Phase Jitter (100 MHz) <sup>(17)</sup>	10 kHz to 1.5 MHz (PCIe)	—	—	3	—	—	3	—	—	3	ps (rms)
$R_{REF}$ <sup>(19)</sup>	—	—	1800 $\pm 1\%$	—	—	1800 $\pm 1\%$	—	—	1800 $\pm 1\%$	—	$\Omega$
<b>Transceiver Clocks</b>											
fixedclk clock frequency	PCIe Receiver Detect	—	100 or 125	—	—	100 or 125	—	—	100 or 125	—	MHz

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 5 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Programmable DC gain	DC Gain Setting = 0	—	0	—	—	0	—	—	0	—	dB
	DC Gain Setting = 1	—	2	—	—	2	—	—	2	—	dB
	DC Gain Setting = 2	—	4	—	—	4	—	—	4	—	dB
	DC Gain Setting = 3	—	6	—	—	6	—	—	6	—	dB
	DC Gain Setting = 4	—	8	—	—	8	—	—	8	—	dB
<b>Transmitter</b>											
Supported I/O Standards	—	1.4-V and 1.5-V PCML									
Data rate (Standard PCS)	—	600	—	12200	600	—	12200	600	—	8500/ 10312.5 <sup>(24)</sup>	Mbps
Data rate (10G PCS)	—	600	—	14100	600	—	12500	600	—	8500/ 10312.5 <sup>(24)</sup>	Mbps
Differential on- chip termination resistors	85- $\Omega$ setting	—	85 $\pm$ 20%	—	—	85 $\pm$ 20%	—	—	85 $\pm$ 20%	—	$\Omega$
	100- $\Omega$ setting	—	100 $\pm$ 20%	—	—	100 $\pm$ 20%	—	—	100 $\pm$ 20%	—	$\Omega$
	120- $\Omega$ setting	—	120 $\pm$ 20%	—	—	120 $\pm$ 20%	—	—	120 $\pm$ 20%	—	$\Omega$
	150- $\Omega$ setting	—	150 $\pm$ 20%	—	—	150 $\pm$ 20%	—	—	150 $\pm$ 20%	—	$\Omega$
V <sub>OCM</sub> (AC coupled)	0.65-V setting	—	650	—	—	650	—	—	650	—	mV
V <sub>OCM</sub> (DC coupled)	—	—	650	—	—	650	—	—	650	—	mV
Rise time <sup>(7)</sup>	20% to 80%	30	—	160	30	—	160	30	—	160	ps
Fall time <sup>(7)</sup>	80% to 20%	30	—	160	30	—	160	30	—	160	ps
Intra-differential pair skew	Tx V <sub>CM</sub> = 0.5 V and slew rate of 15 ps	—	—	15	—	—	15	—	—	15	ps
Intra-transceiver block transmitter channel-to- channel skew	x6 PMA bonded mode	—	—	120	—	—	120	—	—	120	ps

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices <sup>(1)</sup> (Part 6 of 7)**

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	—	—	500	—	—	500	—	—	500	ps
<b>CMU PLL</b>											
Supported Data Range	—	600	—	12500	600	—	12500	600	—	8500/ 10312.5 (24)	Mbps
t <sub>pll_powerdown</sub> <sup>(15)</sup>	—	1	—	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(16)</sup>	—	—	—	10	—	—	10	—	—	10	μs
<b>ATX PLL</b>											
Supported Data Rate Range	VCO post-divider L=2	8000	—	14100	8000	—	12500	8000	—	8500/ 10312.5 (24)	Mbps
	L=4	4000	—	7050	4000	—	6600	4000	—	6600	Mbps
	L=8	2000	—	3525	2000	—	3300	2000	—	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	—	1762.5	1000	—	1762.5	1000	—	1762.5	Mbps
t <sub>pll_powerdown</sub> <sup>(15)</sup>	—	1	—	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(16)</sup>	—	—	—	10	—	—	10	—	—	10	μs
<b>fPLL</b>											
Supported Data Range	—	600	—	3250/ 3125 <sup>(25)</sup>	600	—	3250/ 3125 <sup>(25)</sup>	600	—	3250/ 3125 <sup>(25)</sup>	Mbps
t <sub>pll_powerdown</sub> <sup>(15)</sup>	—	1	—	—	1	—	—	1	—	—	μs



Table 27 shows the  $V_{OD}$  settings for the GX channel.

**Table 27. Typical  $V_{OD}$  Setting for GX Channel, TX Termination = 100  $\Omega$  <sup>(2)</sup>**

Symbol	$V_{OD}$ Setting	$V_{OD}$ Value (mV)	$V_{OD}$ Setting	$V_{OD}$ Value (mV)
<b><math>V_{OD}</math> differential peak to peak typical <sup>(3)</sup></b>	0 <sup>(1)</sup>	0	32	640
	1 <sup>(1)</sup>	20	33	660
	2 <sup>(1)</sup>	40	34	680
	3 <sup>(1)</sup>	60	35	700
	4 <sup>(1)</sup>	80	36	720
	5 <sup>(1)</sup>	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
	15	300	47	940
	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

**Note to Table 27:**

- (1) If TX termination resistance = 100 $\Omega$ , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
Data rate	GT channels	19,600	—	28,050	19,600	—	25,780	Mbps
Differential on-chip termination resistors	GT channels	—	100	—	—	100	—	Ω
	GX channels	(8)						
V <sub>OCM</sub> (AC coupled)	GT channels	—	500	—	—	500	—	mV
	GX channels	(8)						
Rise/Fall time	GT channels	—	15	—	—	15	—	ps
	GX channels	(8)						
Intra-differential pair skew	GX channels	(8)						
Intra-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
Inter-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
CMU PLL								
Supported Data Range	—	600	—	12500	600	—	8500	Mbps
t <sub>pll_powerdown</sub> <sup>(13)</sup>	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(14)</sup>	—	—	—	10	—	—	10	μs
ATX PLL								
Supported Data Rate Range for GX Channels	VCO post- divider L=2	8000	—	12500	8000	—	8500	Mbps
	L=4	4000	—	6600	4000	—	6600	Mbps
	L=8	2000	—	3300	2000	—	3300	Mbps
	L=8, Local/Central Clock Divider =2	1000	—	1762.5	1000	—	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	—	14025	9800	—	12890	Mbps
t <sub>pll_powerdown</sub> <sup>(13)</sup>	—	1	—	—	1	—	—	μs
t <sub>pll_lock</sub> <sup>(14)</sup>	—	—	—	10	—	—	10	μs
fPLL								
Supported Data Range	—	600	—	3250/ 3.125 <sup>(23)</sup>	600	—	3250/ 3.125 <sup>(23)</sup>	Mbps
t <sub>pll_powerdown</sub> <sup>(13)</sup>	—	1	—	—	1	—	—	μs

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) <sup>(1)</sup>**

Symbol/ Description	Conditions	Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Typ	Max	Min	Typ	Max	
$t_{pll\_lock}$ <sup>(14)</sup>	—	—	—	10	—	—	10	μs

**Notes to Table 28:**

- (1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the VCCR\_GXB power supply level.
- (3) The device cannot tolerate prolonged operation at this absolute maximum.
- (4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (6) Refer to Figure 6 for the GT channel DC gain curves.
- (7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.
- (9)  $t_{LTR}$  is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (10)  $t_{LTD}$  is time required for the receiver CDR to start recovering valid data after the  $rx\_is\_lockedto\ data$  signal goes high.
- (11)  $t_{LTD\_manual}$  is the time required for the receiver CDR to start recovering valid data after the  $rx\_is\_lockedto\ data$  signal goes high when the CDR is functioning in the manual mode.
- (12)  $t_{LTR\_LTD\_manual}$  is the time the receiver CDR must be kept in lock to reference (LTR) mode after the  $rx\_is\_lockedto\ ref$  signal goes high when the CDR is functioning in the manual mode.
- (13)  $tp11\_powerdown$  is the PLL powerdown minimum pulse width.
- (14)  $tp11\_lock$  is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (15) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula:  
REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (16) The maximum peak to peak differential input voltage  $V_{ID}$  after device configuration is equal to  $4 \times (\text{absolute } V_{MAX} \text{ for receiver pin} - V_{ICM})$ .
- (17) For ES devices, RREF is 2000 Ω ±1%.
- (18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20\*log(f/622).
- (19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (20) Refer to Figure 4.
- (21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (22) This supply follows VCCR\_GXB for both GX and GT channels.
- (23) When you use fPLL as a TXPLL of the transceiver.

## PLL Specifications

Table 31 lists the Stratix V PLL specifications when operating in both the commercial junction temperature range (0° to 85°C) and the industrial junction temperature range (–40° to 100°C).

**Table 31. PLL Specifications for Stratix V Devices (Part 1 of 3)**

Symbol	Parameter	Min	Typ	Max	Unit
$f_{IN}$	Input clock frequency (C1, C2, C2L, I2, and I2L speed grades)	5	—	800 <sup>(1)</sup>	MHz
	Input clock frequency (C3, I3, I3L, and I3YY speed grades)	5	—	800 <sup>(1)</sup>	MHz
	Input clock frequency (C4, I4 speed grades)	5	—	650 <sup>(1)</sup>	MHz
$f_{INPFD}$	Input frequency to the PFD	5	—	325	MHz
$f_{FINPFD}$	Fractional Input clock frequency to the PFD	50	—	160	MHz
$f_{VCO}$ <sup>(9)</sup>	PLL VCO operating range (C1, C2, C2L, I2, I2L speed grades)	600	—	1600	MHz
	PLL VCO operating range (C3, I3, I3L, I3YY speed grades)	600	—	1600	MHz
	PLL VCO operating range (C4, I4 speed grades)	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	40	—	60	%
$f_{OUT}$	Output frequency for an internal global or regional clock (C1, C2, C2L, I2, I2L speed grades)	—	—	717 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C3, I3, I3L speed grades)	—	—	650 <sup>(2)</sup>	MHz
	Output frequency for an internal global or regional clock (C4, I4 speed grades)	—	—	580 <sup>(2)</sup>	MHz
$f_{OUT\_EXT}$	Output frequency for an external clock output (C1, C2, C2L, I2, I2L speed grades)	—	—	800 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C3, I3, I3L speed grades)	—	—	667 <sup>(2)</sup>	MHz
	Output frequency for an external clock output (C4, I4 speed grades)	—	—	553 <sup>(2)</sup>	MHz
$t_{OUTDUTY}$	Duty cycle for a dedicated external clock output (when set to 50%)	45	50	55	%
$t_{FCOMP}$	External feedback clock compensation time	—	—	10	ns
$f_{DYCONFIGCLK}$	Dynamic Configuration Clock used for <code>mgmt_clk</code> and <code>scanclk</code>	—	—	100	MHz
$t_{LOCK}$	Time required to lock from the end-of-device configuration or deassertion of <code>areset</code>	—	—	1	ms
$t_{DLOCK}$	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	1	ms
$f_{CLBW}$	PLL closed-loop low bandwidth	—	0.3	—	MHz
	PLL closed-loop medium bandwidth	—	1.5	—	MHz
	PLL closed-loop high bandwidth <sup>(7)</sup>	—	4	—	MHz
$t_{PLL\_PSERR}$	Accuracy of PLL phase shift	—	—	±50	ps
$t_{ARESET}$	Minimum pulse width on the <code>areset</code> signal	10	—	—	ns

**Table 32. Block Performance Specifications for Stratix V DSP Devices (Part 2 of 2)**

Mode	Peformance							Unit
	C1	C2, C2L	I2, I2L	C3	I3, I3L, I3YY	C4	I4	
Modes using Three DSPs								
One complex 18 x 25	425	425	415	340	340	275	265	MHz
Modes using Four DSPs								
One complex 27 x 27	465	465	465	380	380	300	290	MHz

### Memory Block Specifications

Table 33 lists the Stratix V memory block specifications.

**Table 33. Memory Block Performance Specifications for Stratix V Devices <sup>(1)</sup>, <sup>(2)</sup> (Part 1 of 2)**

Memory	Mode	Resources Used		Performance							Unit
		ALUTs	Memory	C1	C2, C2L	C3	C4	I2, I2L	I3, I3L, I3YY	I4	
MLAB	Single port, all supported widths	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x32/x64 depth	0	1	450	450	400	315	450	400	315	MHz
	Simple dual-port, x16 depth <sup>(3)</sup>	0	1	675	675	533	400	675	533	400	MHz
	ROM, all supported widths	0	1	600	600	500	450	600	500	450	MHz

Figure 7 shows the dynamic phase alignment (DPA) lock time specifications with the DPA PLL calibration option enabled.

**Figure 7. DPA Lock Time Specification with DPA PLL Calibration Enabled**



Table 37 lists the DPA lock time specifications for Stratix V devices.

**Table 37. DPA Lock Time Specifications for Stratix V GX Devices Only <sup>(1), (2), (3)</sup>**

Standard	Training Pattern	Number of Data Transitions in One Repetition of the Training Pattern	Number of Repetitions per 256 Data Transitions <sup>(4)</sup>	Maximum
SPI-4	00000000001111111111	2	128	640 data transitions
Parallel Rapid I/O	00001111	2	128	640 data transitions
	10010000	4	64	640 data transitions
Miscellaneous	10101010	8	32	640 data transitions
	01010101	8	32	640 data transitions

**Notes to Table 37:**

- (1) The DPA lock time is for one channel.
- (2) One data transition is defined as a 0-to-1 or 1-to-0 transition.
- (3) The DPA lock time stated in this table applies to both commercial and industrial grade.
- (4) This is the number of repetitions for the stated training pattern to achieve the 256 data transitions.

Figure 8 shows the LVDS soft-clock data recovery (CDR)/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps. Table 38 lists the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $\geq 1.25$  Gbps.

**Figure 8. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $\geq 1.25$  Gbps**



**Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq 1.25$  Gbps**

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Figure 9 shows the LVDS soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate  $< 1.25$  Gbps.

**Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $< 1.25$  Gbps**

### DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

**Table 39. DLL Range Specifications for Stratix V Devices <sup>(1)</sup>**

C1	C2, C2L, I2, I2L	C3, I3, I3L, I3YY	C4,I4	Unit
300-933	300-933	300-890	300-890	MHz

**Note to Table 39:**

- (1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

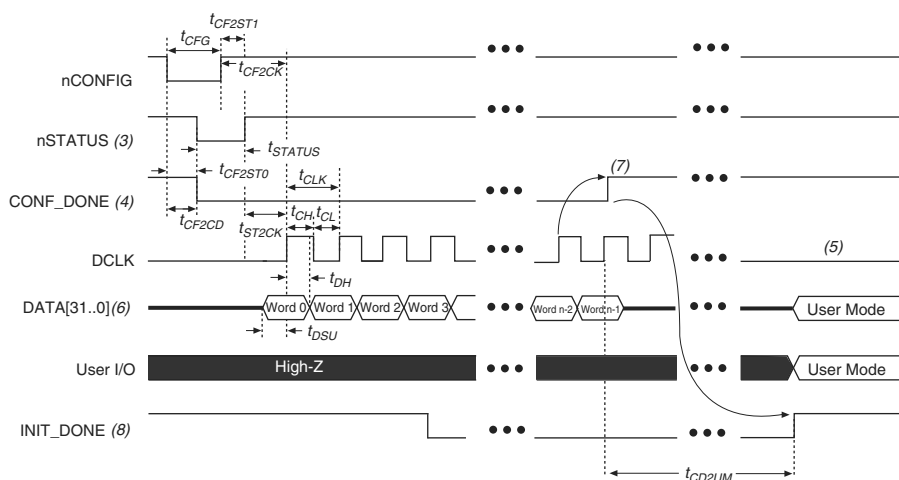
**Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)**

Speed Grade	Min	Max	Unit
C1	8	14	ps
C2, C2L, I2, I2L	8	14	ps
C3,I3, I3L, I3YY	8	15	ps

## FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is 1.

**Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 <sup>(1), (2)</sup>**



### Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA [] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF\_DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP  $\times 16$ , use DATA [15..0]. For FPP  $\times 8$ , use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF\_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.



## Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

**Table 52. DCLK Frequency Specification in the AS Configuration Scheme <sup>(1), (2)</sup>**

Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

**Notes to Table 52:**

- (1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

**Figure 14. AS Configuration Timing**



**Notes to Figure 14:**

- (1) If you are using AS ×4 mode, this signal represents the AS\_DATA [3 : 0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or CLKUSR pin.
- (3) After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 53 lists the timing parameters for AS ×1 and AS ×4 configurations in Stratix V devices.

**Table 53. AS Timing Parameters for AS ×1 and AS ×4 Configurations in Stratix V Devices <sup>(1), (2)</sup> (Part 1 of 2)**

Symbol	Parameter	Minimum	Maximum	Units
$t_{CO}$	DCLK falling edge to AS_DATA0/ASDO output	—	2	ns
$t_{SU}$	Data setup time before falling edge on DCLK	1.5	—	ns
$t_{H}$	Data hold time after falling edge on DCLK	0	—	ns

## Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

**Table 56. Remote System Upgrade Circuitry Timing Specifications**

Parameter	Minimum	Maximum	Unit
$t_{RU\_nCONFIG}^{(1)}$	250	—	ns
$t_{RU\_nRSTIMER}^{(2)}$	250	—	ns

**Notes to Table 56:**

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.
- (2) This is equivalent to strobing the reset\_timer input of the ALTREMOTE\_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the “Configuration, Design Security, and Remote System Upgrades in Stratix V Devices” chapter.

## User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

**Table 57. 12.5-MHz Internal Oscillator Specifications**

Minimum	Typical	Maximum	Units
5.3	7.9	12.5	MHz

## I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.



You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

## Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

**Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)**

Parameter (1)	Available Settings	Min Offset (2)	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	I2	I3, I3YY	I4	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

**Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)**

Parameter (1)	Available Settings	Min Offset (2)	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	I2	I3, I3YY	I4	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

**Notes to Table 58:**

- (1) You can set this value in the Quartus II software by selecting **D1**, **D2**, **D3**, **D5**, and **D6** in the **Assignment Name** column of **Assignment Editor**.
- (2) Minimum offset does not include the intrinsic delay.

## Programmable Output Buffer Delay

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

**Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)**

Symbol	Parameter	Typical	Unit
D <sub>OUTBUF</sub>	Rising and/or falling edge delay	0 (default)	ps
		25	ps
		50	ps
		75	ps

**Note to Table 59:**

- (1) You can set the programmable output buffer delay in the Quartus II software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

## Glossary

Table 60 lists the glossary for this chapter.

**Table 60. Glossary (Part 1 of 4)**

Letter	Subject	Definitions
A	—	—
B		
C		
D	—	—
E	—	—
F	f <sub>HCLK</sub>	Left and right PLL input clock frequency.
	f <sub>HSDR</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDR</sub> = 1/TUI), non-DPA.
	f <sub>HSDRDPA</sub>	High-speed I/O block—Maximum and minimum <b>LVDS</b> data transfer rate (f <sub>HSDRDPA</sub> = 1/TUI), DPA.

**Table 60. Glossary (Part 4 of 4)**

Letter	Subject	Definitions
<b>V</b>	$V_{CM(DC)}$	DC common mode input voltage.
	$V_{ICM}$	Input common mode voltage—The common mode of the differential signal at the receiver.
	$V_{ID}$	Input differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the receiver.
	$V_{DIF(AC)}$	AC differential input voltage—Minimum AC input differential voltage required for switching.
	$V_{DIF(DC)}$	DC differential input voltage— Minimum DC input differential voltage required for switching.
	$V_{IH}$	Voltage input high—The minimum positive voltage applied to the input which is accepted by the device as a logic high.
	$V_{IH(AC)}$	High-level AC input voltage
	$V_{IH(DC)}$	High-level DC input voltage
	$V_{IL}$	Voltage input low—The maximum positive voltage applied to the input which is accepted by the device as a logic low.
	$V_{IL(AC)}$	Low-level AC input voltage
	$V_{IL(DC)}$	Low-level DC input voltage
	$V_{OCM}$	Output common mode voltage—The common mode of the differential signal at the transmitter.
	$V_{OD}$	Output differential voltage swing—The difference in voltage between the positive and complementary conductors of a differential transmission at the transmitter.
	$V_{SWING}$	Differential input voltage
	$V_X$	Input differential cross point voltage
	$V_{OX}$	Output differential cross point voltage
<b>W</b>	W	High-speed I/O block—clock boost factor
<b>X</b>	—	—
<b>Y</b>		
<b>Z</b>		

## Document Revision History

Table 61 lists the revision history for this chapter.

**Table 61. Document Revision History (Part 1 of 3)**

Date	Version	Changes
June 2018	3.9	<ul style="list-style-type: none"> <li>Added the “Stratix V Device Overshoot Duration” figure.</li> </ul>
April 2017	3.8	<ul style="list-style-type: none"> <li>Added a footnote to the “High-Speed I/O Specifications for Stratix V Devices” table.</li> <li>Changed the minimum value for <math>t_{CD2UMC}</math> in the “PS Timing Parameters for Stratix V Devices” table.</li> <li>Changed the condition for <math>100\text{-}\Omega</math> <math>R_D</math> in the “OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices” table.</li> <li>Changed the minimum value for <math>t_{CD2UMC}</math> in the “AS Timing Parameters for AS ‘1 and AS ‘4 Configurations in Stratix V Devices” table</li> <li>Changed the minimum value for <math>t_{CD2UMC}</math> in the “FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is &gt;1” table.</li> <li>Changed the minimum value for <math>t_{CD2UMC}</math> in the “FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is &gt;1” table.</li> <li>Changed the minimum number of clock cycles value in the “Initialization Clock Source Option and the Maximum Frequency” table.</li> </ul>
June 2016	3.7	<ul style="list-style-type: none"> <li>Added the <math>V_{ID}</math> minimum specification for LVPECL in the “Differential I/O Standard Specifications for Stratix V Devices” table</li> <li>Added the <math>I_{OUT}</math> specification to the “Absolute Maximum Ratings for Stratix V Devices” table.</li> </ul>
December 2015	3.6	<ul style="list-style-type: none"> <li>Added a footnote to the “High-Speed I/O Specifications for Stratix V Devices” table.</li> </ul>
December 2015	3.5	<ul style="list-style-type: none"> <li>Changed the transmitter, receiver, and ATX PLL data rate specifications in the “Transceiver Specifications for Stratix V GX and GS Devices” table.</li> <li>Changed the configuration .rbf sizes in the “Uncompressed .rbf Sizes for Stratix V Devices” table.</li> </ul>
July 2015	3.4	<ul style="list-style-type: none"> <li>Changed the data rate specification for transceiver speed grade 3 in the following tables:               <ul style="list-style-type: none"> <li>“Transceiver Specifications for Stratix V GX and GS Devices”</li> <li>“Stratix V Standard PCS Approximate Maximum Date Rate”</li> <li>“Stratix V 10G PCS Approximate Maximum Data Rate”</li> </ul> </li> <li>Changed the conditions for reference clock rise and fall time, and added a note to the “Transceiver Specifications for Stratix V GX and GS Devices” table.</li> <li>Added a note to the “Minimum differential eye opening at receiver serial input pins” specification in the “Transceiver Specifications for Stratix V GX and GS Devices” table.</li> <li>Changed the <math>t_{CO}</math> maximum value in the “AS Timing Parameters for AS ‘1 and AS ‘4 Configurations in Stratix V Devices” table.</li> <li>Removed the CDR ppm tolerance specification from the “Transceiver Specifications for Stratix V GX and GS Devices” table.</li> </ul>